

# MATERIAL DECLARATION SHEET



Material Number	CM322522 /PM1210 Series			
Product Line	Wound Chip Inductor			
Compliance Date	2025/03/31			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Core	Ferrite	0.01	Iron oxide (Fe2O3)	1309-37-1	66.0%	13.2	20.00
				Nickel oxide (NiO)	1313-99-1	8.00%	1.60	
				Zinc oxide (ZnO)	1314-13-2	22.0%	4.40	
				Copper oxide(CuO)	1317-38-0	4.00%	0.80	
2	Wire	COPPER	0.0095	Copper(Cu)	7440-50-8	99.95%	18.99	20.00
				Misc. ,not to declare	/	0.05%	0.01	
		RESIN	0.0005	Polyesterimide	37317-16-1	100.0%	1.00	
3	Terminal	COPPER	0.019	Copper (Cu)	7440-50-8	100.0%	38.2	40.00
		plating-Sn	0.001	Tin (Sn)	7440-31-5	100.0%	1.80	
4	Adhesive	Epoxy	0.002	Bisphenol A diglycidyl ether	25068-38-6	72.0%	2.88	4.00
				Polyacrylic acid; 2-Propenoic acid homopolymer; A	9003-01-4	1.00%	0.04	

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				Titanium dioxide	13463-67-7	2.00%	0.08	
				Silicon dioxide	7631-86-9	25.0%	1.00	
6	Molding Compound	Resin	0.006	silica	60676-86-0	69.0%	8.28	12.00
				Antimony(III) oxide	1309-64-4	2.50%	0.30	
				Formaldehyde, polymer with 2-(chloromethyl)oxirane and 2-methylphenol	29690-82-2	15.0%	1.80	
				Phenol-Formaldehyde Resin	9003-35-4	10.0%	1.20	
				Brominated epoxy resin	40039-93-8	2.50%	0.30	
				Carbon black	1333-86-4	1.00%	0.12	
7	Solder Bar	Tin	0.001	Tin (Sn)	7440-31-5	100.0%	2.00	2.00
8	Solder Wire	Tin	0.001	Tin (Sn)	7440-31-5	100.0%	2.00	2.00
		Total weight	<b>0.050</b>					

**This Document was updated on:** 2025/3/31

### Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.